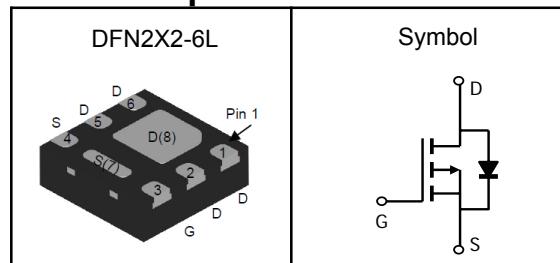


P-Channel Enhancement Mode MOSFET

Features

- Low $R_{DS(on)}$ for low conduction loss
- Reliable and Rugged
- ROHS Compliant & Halogen-Free

Pin Description



Applications

- Power Management in Desktop Computer
- DC/DC Converters

V_{DSS}	-12	V
$R_{DS(ON)-Typ}$	11	$\mu\Omega$
I_D	-16	A

Absolute Maximum Ratings ($T_A=25^\circ C$, Unless Otherwise Noted)

Symbol	Parameter	P-Channel	Unit
V_{DSS}	Drain-Source Voltage	-12	V
V_{GSS}	Gate-Source Voltage	± 12	V
T_J	Maximum Junction Temperature	-55 to 150	$^\circ C$
T_{STG}	Storage Temperature Range	-55 to 150	$^\circ C$
$I_{DM}^{①}$	Pulse Drain Current Tested	-65	A
I_D	Continuous Drain Current	-16	A
P_D	Maximum Power Dissipation	2.5	W

Thermal Characteristics

Symbol	Parameter	Rating	Unit
$R_{θJA}^{③}$	Thermal Resistance-Junction to Ambient	50	$^\circ C/W$

Note ① : Max. current is limited by bonding wire.

Note ② : UIS tested and pulse width are limited by maximum junction temperature 150°C.

Note ③ : Surface Mounted on 1in² FR-4 board with 1oz.

P-Channel Enhancement Mode MOSFET

Electrical Characteristics ($T_J=25^\circ\text{C}$, Unless Otherwise Noted)

Symbol	Parameter	Test Conditions	Min	Typ	Max	Unit
Static Electrical Characteristics						
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}$, $I_{\text{D}}=-250\mu\text{A}$	-12	---	---	V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{\text{DS}}=-12\text{V}$, $V_{\text{GS}}=0\text{V}$	---	---	-1	μA
$V_{\text{GS}(\text{th})}$	Gate Threshold Voltage	$V_{\text{DS}}=V_{\text{GS}}$, $I_{\text{D}}=-250\mu\text{A}$	-0.4	---	-1.0	V
I_{GSS}	Gate Leakage Current	$V_{\text{GS}}=\pm 12\text{V}$, $V_{\text{DS}}=0\text{V}$	---	---	± 100	nA
$R_{\text{DS}(\text{ON})}$	Drain-Source On-state Resistance	$V_{\text{GS}}=-4.5\text{V}$, $I_{\text{D}}=-6.7\text{A}$	---	11	18	$\text{m}\Omega$
		$V_{\text{GS}}=-2.5\text{V}$, $I_{\text{D}}=-6.2\text{A}$	---	14	22	
g_{fs}	Forward Transconductance	$V_{\text{DS}}=-5\text{V}$, $I_{\text{D}}=-6.7\text{A}$	20	---	---	S
Dynamic Characteristics^⑤						
C_{iss}	Input Capacitance	$V_{\text{GS}}=0\text{V}$, $V_{\text{DS}}=-10\text{V}$, Freq.=1MHz	---	2680	---	pF
C_{oss}	Output Capacitance		---	680	---	
C_{rss}	Reverse Transfer Capacitance		---	570	---	
$T_{\text{d}(\text{on})}$	Turn-on Delay Time	$V_{\text{DD}}=-10\text{V}$, $V_{\text{GS}}=-4.5\text{V}$, $R_{\text{G}}=10\Omega$, $I_{\text{D}}=-1\text{A}$	---	11	---	nS
T_{r}	Turn-on Rise Time		---	35	---	
$T_{\text{d}(\text{off})}$	Turn-off Delay Time		---	30	---	
T_{f}	Turn-off Fall Time		---	10	---	
Q_{g}	Total Gate Charge	$V_{\text{DS}}=-6\text{V}$, $V_{\text{GS}}=-4.5\text{V}$, $I_{\text{D}}=-10\text{A}$	---	35	---	nC
Q_{gs}	Gate-Source Charge		---	5	---	
Q_{gd}	Gate-Drain Charge		---	10	---	
Source-Drain Characteristics						
$V_{\text{SD}}^{④}$	Diode Forward Voltage	$I_{\text{s}}=-8\text{A}$, $V_{\text{GS}}=0\text{V}$	---	---	-1.2	V

Note ④: Pulse test (pulse width 300us, duty cycle 2%).

Note ⑤ : Guaranteed by design, not subject to production testing.

P-Channel Enhancement Mode MOSFET

Typical Characteristics

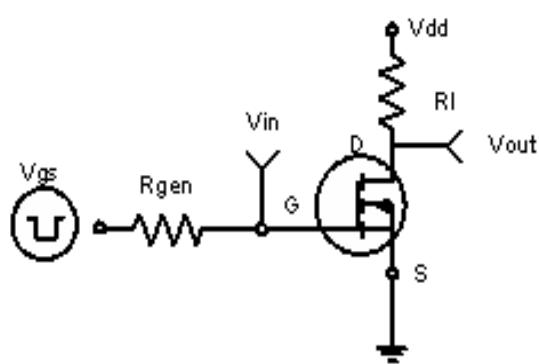


Figure 1:Switching Test Circuit

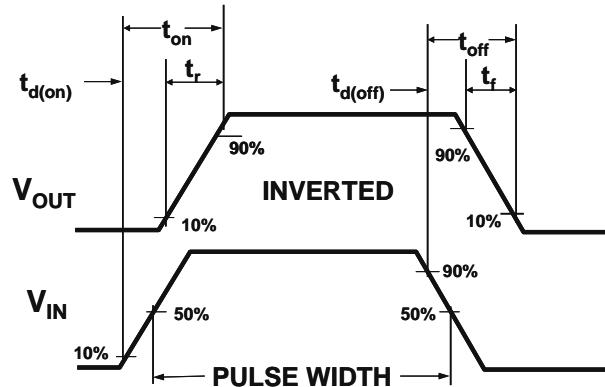


Figure 2:Switching Waveforms

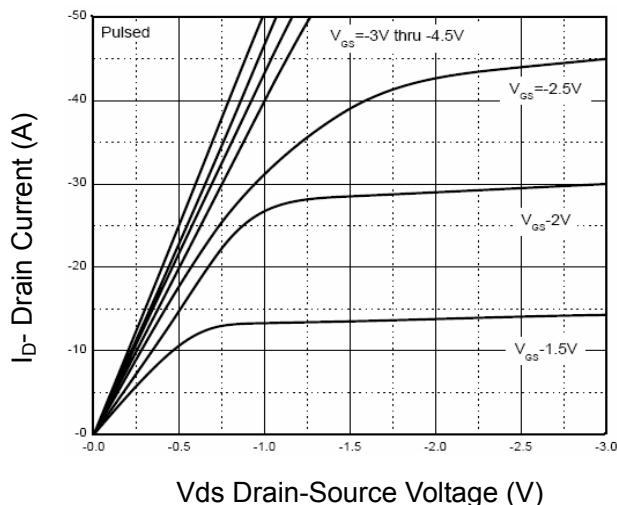


Figure 3 Output Characteristics

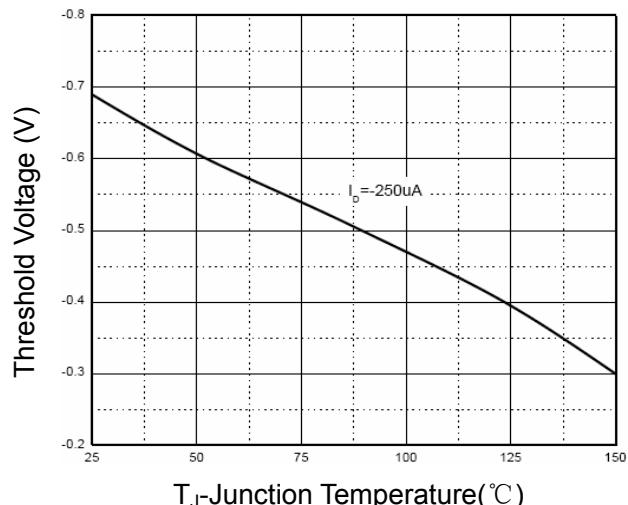


Figure 4 Drain Current

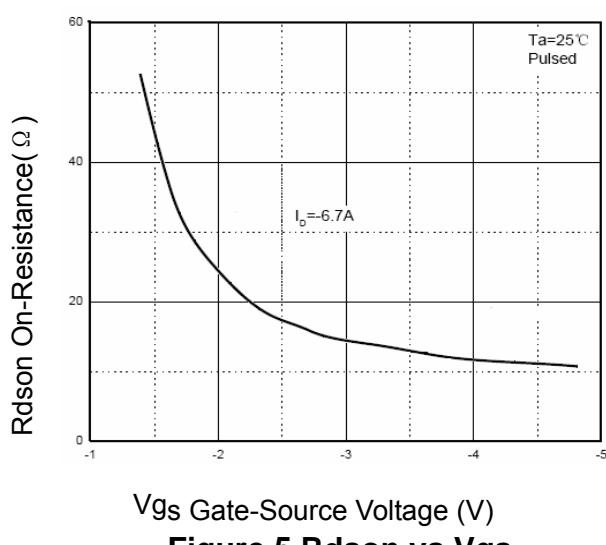


Figure 5 Rdson vs Vgs

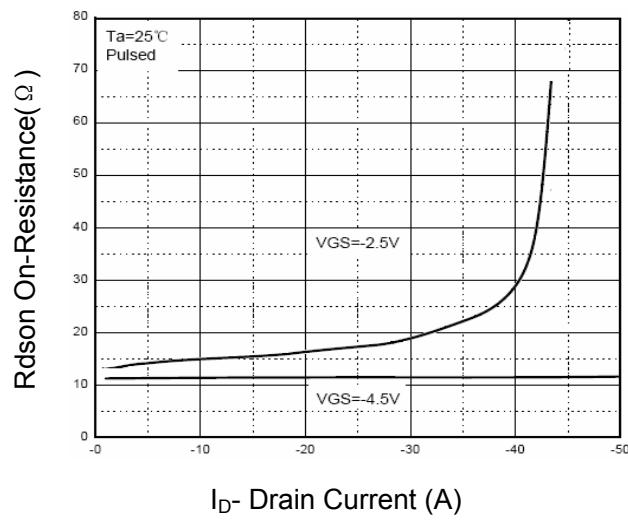
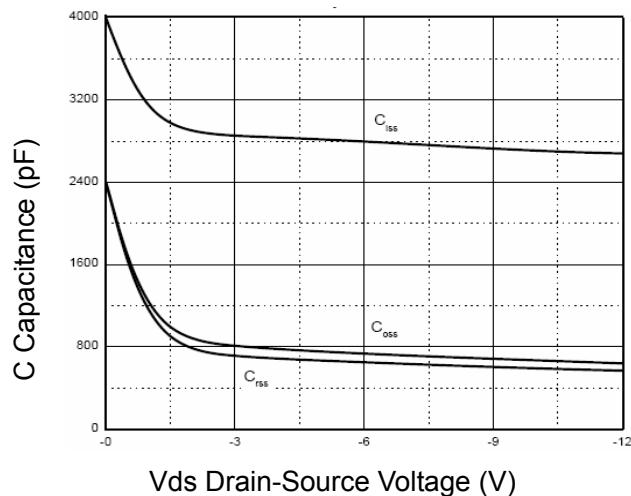


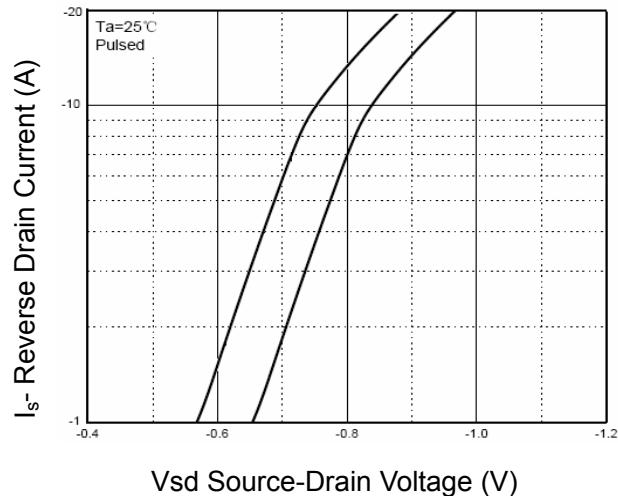
Figure 6 Drain-Source On-Resistance

P-Channel Enhancement Mode MOSFET



Vds Drain-Source Voltage (V)

Figure 7 Capacitance vs Vds

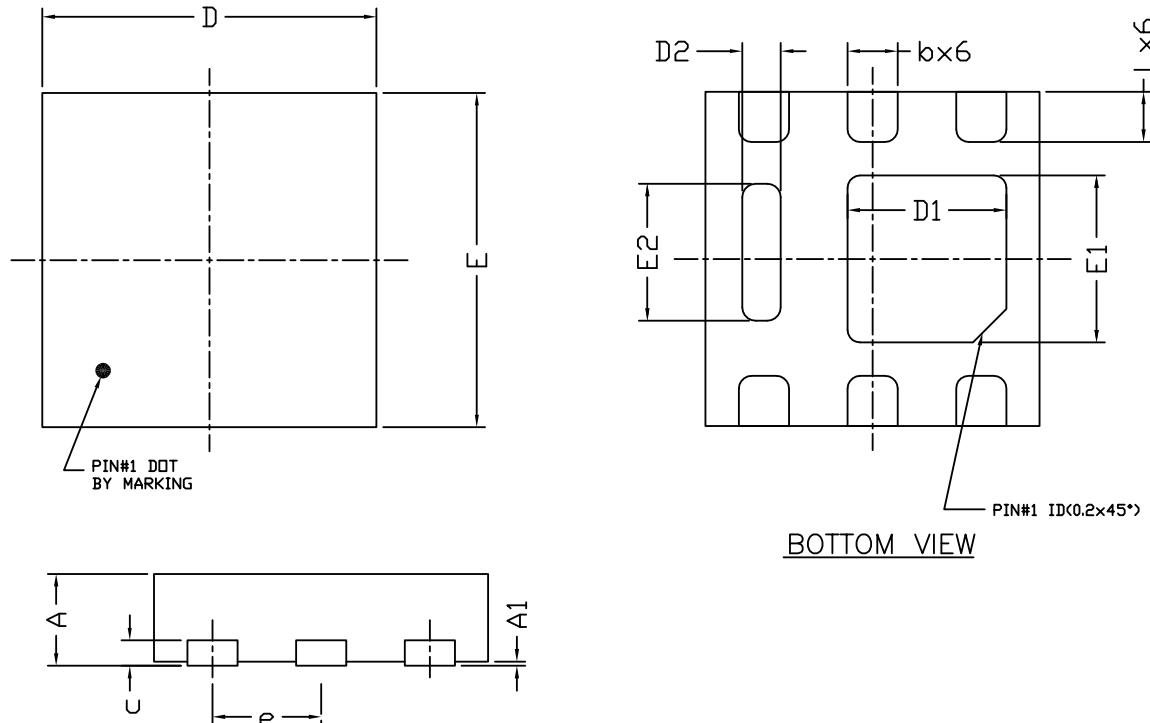


Vsd Source-Drain Voltage (V)

Figure 8 Source- Drain Diode Forward

P-Channel Enhancement Mode MOSFET

DFN2X2-6L Package Outline Dimensions



Symbol	Dimensions (unit:mm)			Symbol	Dimensions (unit:mm)		
	Min	Typ	Max		Min	Typ	Max
A	0.50	0.55	0.60	D2	0.13	0.25	0.40
A1	0.00	---	0.05	E	1.90	2.00	2.10
b	0.25	0.30	0.35	E1	0.82	1.00	1.20
c	0.15 REF			E2	0.45	0.75	0.90
D	1.90	2.00	2.10	e	0.65 REF		
D1	0.85	0.95	1.05	L	0.20	0.25	0.32